

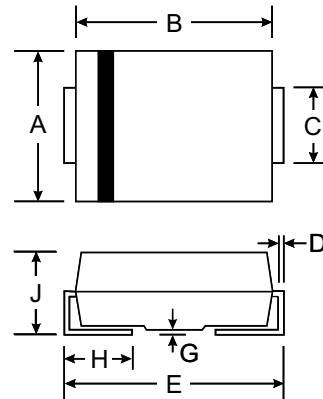
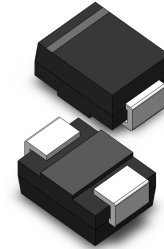
**VOLTAGE RANGE: 150 - 200V**  
**CURRENT: 1.0 A**

### Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O

### Mechanical Data

- Case: SMB/DO-214AA, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)



SMB(DO-214AA)		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.70
C	1.91	2.21
D	0.15	0.31
E	5.00	5.59
G	0.10	0.20
H	0.76	1.52
J	2.00	2.62
All Dimensions in mm		

### Maximum Ratings and Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

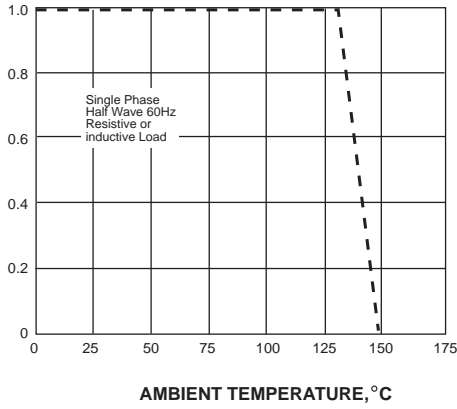
Characteristic	Symbol	B1150B	B1200B	Unit
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	150	200	V
Maximum RMS voltage	V <sub>RMS</sub>	105	140	V
Maximum DC blocking voltage	V <sub>DC</sub>	150	200	V
Maximum average forward rectified current at T <sub>L</sub> (see fig.1)	I <sub>(AV)</sub>	1.0		A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	30.0		A
Maximum instantaneous forward voltage at 1.0A	V <sub>F</sub>	0.85	0.95	V
Maximum DC reverse current T <sub>A</sub> =25°C at rated DC blocking voltage T <sub>A</sub> =100°C	I <sub>R</sub>	0.2 2.0		mA
Typical junction capacitance (NOTE 1)	C <sub>J</sub>	90		pF
Typical thermal resistance (NOTE 2)	R <sub>θJA</sub>	88.0		°C/W
Operating junction temperature range	T <sub>J</sub>	-50 to +150		°C
Storage temperature range	T <sub>STG</sub>	-50 to +150		°C

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

## RATINGS AND CHARACTERISTIC CURVES B1150B THRU B1200B

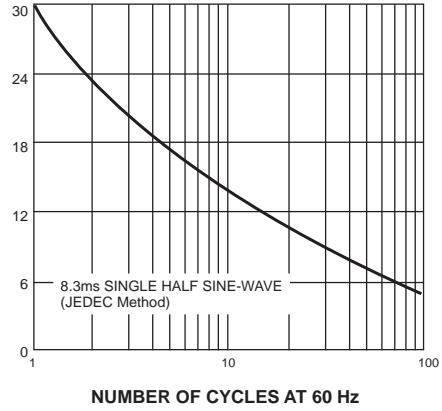
AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



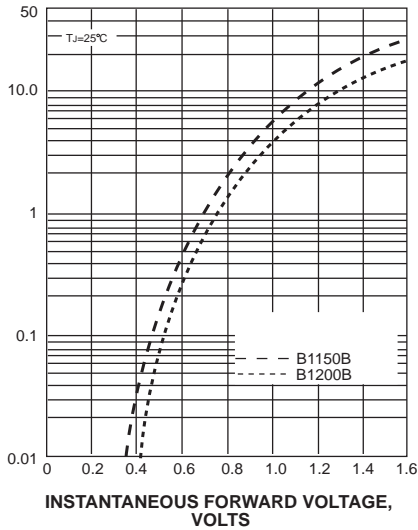
PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



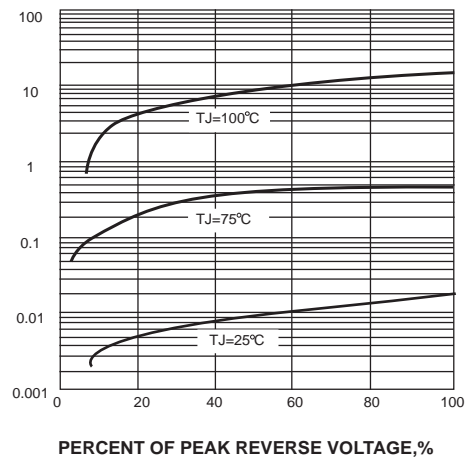
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



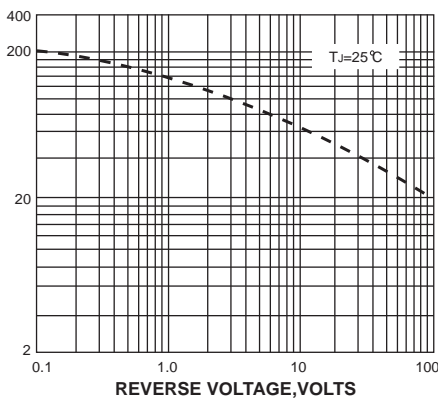
INSTANTANEOUS REVERSE CURRENT, MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE



TRANSIENT THERMAL IMPEDANCE, °C/W

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE

